

ABSTRACT

A method and apparatus for testing a package design and material set comprising using a test die to form a test device and subjecting the test device to a test procedure, such as a highly accelerated stress test (HAST). In one embodiment the device, which comprises a die and a package to be tested, is constructed using a test die. The test die comprises a non-functional die having one or more conductive traces thereon. Use of a test die reduces costs as compared to a functional die and reduces the time to market by allowing package testing prior to creation and testing of a functional die. In one embodiment the test die is configured with conductive traces on its top surface to allow for biasing before, during, or after testing.